Product End-of-Life Disassembly Instructions

Product Category: External Options
Marketing Name / Model [List multiple models if applicable.]
HP 0x2x16 Server Console Switch G2 with Virtual Media/AF618A
HP 1x1Ex 8 IP Console KVM Switch G2 with Virtual Media/AF620A
HP 2x1Ex16 IP Console KVM Switch G2 with Virtual Media/AF621A

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		4
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

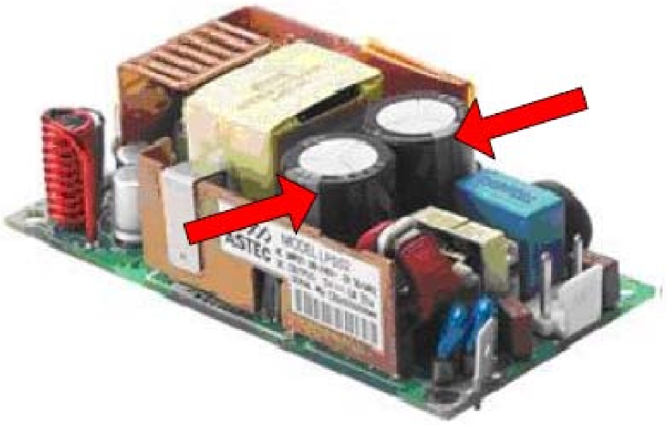
Tool Description	**Tool Size (if applicable)**
Description #1 Philips screw driver	#2
Description #2 Flat head screw driver, small	
Description #3 Flat head screw driver, large	
Description #4 Tie wrap/wire cutter, small	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove mounting brackets or shelves when present
2. Remove top cover
3. Cut tie wrap when present as required
4. Capacitors > 2.5CM – With #2 Philips screw driver remove the screws securing the top cover. Locate the P/S then locate the capacitors and pry from the PCB with a medium flat head screw driver and dispose of properly.
5.
6.
7.
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



Remove these two capacitors on each of the two power supplies.